



Material Content Data Sheet



Sales Product Name	BTS3408G			Issued		19. September 2019		
MA#	MA001089396							
Package	PG-DSO-8-36			Weight*		84.18 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.135	6.10	6.10	61001	61001
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		106	
	non noble metal	zinc	7440-66-6	0.036	0.04		426	
	non noble metal	iron	7439-89-6	0.717	0.85		8519	
	non noble metal	copper	7440-50-8	29.121	34.59	35.49	345924	354975
wire	noble metal	gold	7440-57-5	0.478	0.57	0.57	5683	5683
encapsulation	organic material	carbon black	1333-86-4	0.091	0.11		1076	
	plastics	epoxy resin	-	4.168	4.95		49514	
	inorganic material	silicondioxide	60676-86-0	41.048	48.76	53.82	487601	538191
leadfinish	non noble metal	tin	7440-31-5	0.814	0.97	0.97	9667	9667
plating	noble metal	silver	7440-22-4	0.650	0.77	0.77	7724	7724
glue	plastics	acrylic resin	-	0.421	0.50		5007	
	noble metal	silver	7440-22-4	1.494	1.78	2.28	17752	22759
*deviation	< 10%	Sum in total:			100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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